



General Description

The DSC2211FL2-E0018 is a programmable, high performance dual LVC MOS output oscillator utilizing Micrel's proven silicon MEMS technology to provide excellent jitter and stability while incorporating high output frequency flexibility and drive strength control.

The DSC2211FL2-E0018 allows the user to independently modify the frequency of each output and LVC MOS drive strength using SPI interface.

The user can also select from two pre-programmed default output frequencies using the frequency select pin.

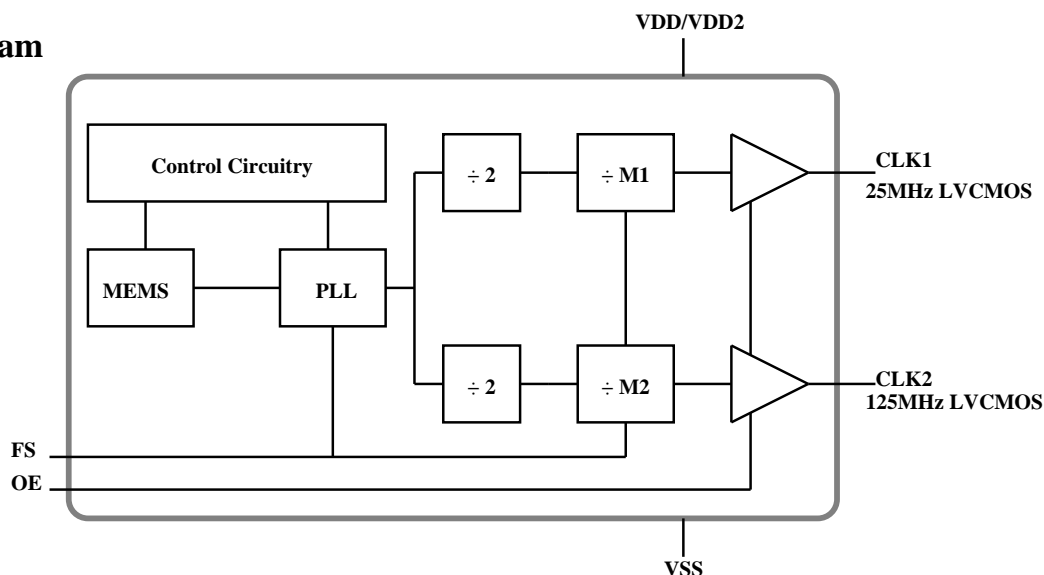
Applications

- Consumer Electronics
- Storage Area Networks
 - SATA, SAS, Fibre Channel
- Passive Optical Networks
 - EPON, 10G-EPON, GPON, 10G-GPON
- Ethernet
 - 1G, 10GBASE-T/KR/LR/SR, and FCoE
- HD/SD/SDI Video & Surveillance
- PCI Express
- Automotive

Features

- Frequency and output formats:
 - LVC MOS 25/27MHz
 - LVC MOS 125/24MHz
- Low RMS phase jitter: <1ps (typ)
- ± 25 ppm frequency stability
- -40°C to +105°C ext. industrial temperature range
- High supply noise rejection: -50dBc
- SPI programmable frequency and drive
- Excellent shock & vibration immunity
 - Qualified to MIL-STD-883
- High reliability
 - 20x better MTF than quartz oscillators
- Supply range of 2.25 to 3.6V
- AEC-Q100 automotive qualified
- 14-pin 3.2mm x 2.5mm QFN package

Block Diagram

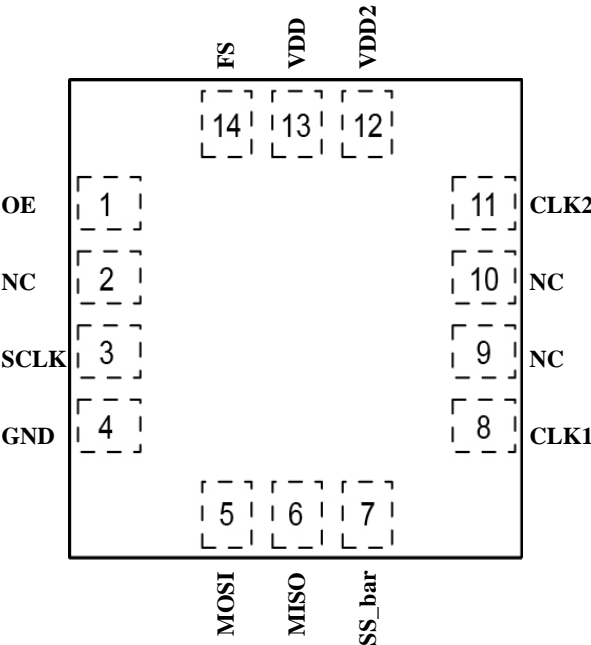


Ordering Information

| Ordering Part Number | Industrial Temperature Range | Shipping | Package |
|----------------------|------------------------------|---------------|--------------------------|
| DSC2211FL2-E0018 | -40°C to +105°C | Tube | 14-pin 3.2mm x 2.5mm QFN |
| DSC2211FL2-E0018T | -40°C to +105°C | Tape and Reel | 14-pin 3.2mm x 2.5mm QFN |

Devices are Green and RoHS compliant. Sample material may have only a partial top mark.

Pin Configuration



14-pin 3.2mm x 2.5mm QFN

Pin Description

| Pin Number | Pin Name | Pin Type | Pin Function |
|------------|----------|----------|--|
| 1 | OE | I | Enables outputs when high and disables outputs when low |
| 2 | NC | | Leave unconnected or connect to ground |
| 3 | SCLK | I | SPI serial clock from master to slave |
| 4 | GND | PWR | Ground |
| 5 | MOSI | | SPI serial data from master to slave |
| 6 | MISO | O | SPI serial data from slave to master |
| 7 | SS_bar | I | SPI slave select (active low) |
| 8 | CLK1 | O | LVC MOS output |
| 9 | NC | | Leave unconnected or connect to ground |
| 10 | NC | | Leave unconnected or connect to ground |
| 11 | CLK2 | O | LVC MOS output |
| 12 | VDD2 | PWR | Power supply for LVC MOS output CLK2, 1.65V to 3.6V (VDD2 ≤ VDD) |
| 13 | VDD | PWR | Power supply |
| 14 | FS | I | Frequency select pin, see Table 2 for details |

Operational Description

The DSC2211FL2-E0018 is a dual output LVC MOS oscillator consisting of a MEMS resonator and a supporting PLL IC. The two LVC MOS outputs are generated through independent 8-bit programmable dividers from the output of the internal PLL. DSC2211FL2-E0018 allows for easy programming of the output frequencies using SPI interface. Upon power-up, the output frequencies are controlled by an internal pre-programmed memory (OTP). This memory stores all coefficients required by the PLL for two different default frequency pairs. The control pin (FS) selects the initial pair. Once the device is powered up, a new output frequency pair can be programmed using SPI pins. Programming details are provided in the Programming Guide.

The DSC2211FL2-E0018 has independent control of the output voltage levels of the two outputs. The high voltage level of CLK1 is equal to the main supply voltage, VDD (pin 13). VDD2 (pin 12) sets the high voltage level of CLK2. VDD2 must be equal to or less than VDD at all times to insure proper operation. VDD2 can be as low as 1.65V. When OE (pin 1) is floated or connected to VDD, the DSC2211FL2-E0018 is in operational mode. Driving OE to ground will disable both output drivers (hi-impedance mode).

DSC2211FL2-E0018 has programmable output drive strength, which can be controlled via SPI.

Table 1 displays typical rise / fall times for the output with a 15pF load capacitance as a function of these control bits at VDD = 3.3V and room temperature.

| | Output Drive Strength Bits [OXS2, OXS1, OXS0] - Default is [111] - X = 1 for CLK1, and 2 for CLK2 | | | | | | | |
|---------|---|-----|-----|-----|-----|-----|-----|------------|
| | 000 | 001 | 010 | 011 | 100 | 101 | 110 | 111 |
| tr (ns) | 2.1 | 1.7 | 1.6 | 1.4 | 1.3 | 1.3 | 1.2 | 1.1 |
| tf (ns) | 2.5 | 2.4 | 2.4 | 2 | 1.8 | 1.6 | 1.3 | 1.3 |

Table 1. Rise/Fall Times for Drive Strengths

Output Clock Frequencies

Frequency select bits are weakly tied high so if left unconnected the default setting will be [1] and the device will output the associated frequency highlighted in bold.

| Freq (MHz) | Freq Select Bit [FS] - Default is [1] | |
|------------|---------------------------------------|------------|
| | 0 | 1 |
| CLK1 | 27 | 25 |
| CLK2 | 24 | 125 |

Table 2. Pin-Selectable Output Frequencies

Absolute Maximum Ratings

| Item | Min. | Max. | Units | Condition |
|----------------|------|-----------|-------|------------|
| Supply Voltage | -0.3 | +4.0 | V | |
| Input Voltage | -0.3 | VDD + 0.3 | V | |
| Junction Temp | - | +150 | °C | |
| Storage Temp | -55 | +150 | °C | |
| Soldering Temp | - | +260 | °C | 40sec max. |
| ESD | | | | |
| HBM | - | 4000 | V | |
| MM | | 400 | | |
| CDM | | 1500 | | |

1000+ years of data retention on internal memory

Specifications (Unless specified otherwise: T = 25°C, max LVCMOS drive strength)

| Parameter | Symbol | Condition | Min. | Typ. | Max. | Units |
|---|--------------|---|-----------------|--------------------|-----------------|-------|
| Supply Voltage ¹ | VDD | | 2.25 | | 3.6 | V |
| Supply Voltage (CLK2) ¹ | VDD2 | | 1.65 | | 3.6 | V |
| Supply Current | IDD | OE pin low - outputs are disabled | | 21 | 23 | mA |
| Supply Current ² | IDD | OE pin high - outputs are enabled CL = 15pF, F01 = F02 = 125MHz | | 32 | | mA |
| Frequency Stability | ΔF | Includes frequency variation due to initial tolerance, temp. and power supply voltage | | | ± 25 | ppm |
| Aging | ΔF | First year (@ 25°C) | | | ± 5 | ppm |
| Startup Time ³ | tSU | T = 25°C | | | 5 | ms |
| Input Logic Levels Input Logic High Input Logic Low | VIH VIL | | 0.75 x VDD - | | - 0.25 x VDD | V |
| Output Disable Time ⁴ | tDA | | | | 5 | ns |
| Output Enable Time | tEN | | | | 20 | ns |
| Pull-Up Resistor ² | | Pull-up exists on all digital IO | | 40 | | kOhms |
| LVCMOS Outputs | | | | | | |
| Output Logic Levels Output Logic High Output Logic Low | VOH VOL | I = ± 6 mA | 0.9 x VDD - | | - 0.1 x VDD | V |
| Output Transition Time ⁴ Rise Time Fall Time | tR tF | 20% to 80% CL = 15pF | | 1.1 1.4 | 2 2 | ns |
| Frequency | CLK1 CLK2 | [FS] = [1] | | 25 125 | | MHz |
| Output Duty Cycle | SYM | | 45 | | 55 | % |
| Period Jitter ⁵ | JPER | F01 = F02 = 125MHz | | 3 | | psRMS |
| Integrated Phase Noise | JPH | 200kHz to 20MHz @ 125MHz 100kHz to 20MHz @ 125MHz 12kHz to 20MHz @ 125MHz | | 0.3 0.38 1.7 | 2 | psRMS |

Notes:

1. Pin 12 VDD2, and pin 13 VDD should be filtered with 0.1uF capacitors.
2. Output is enabled if OE pin is floated or not connected.
3. tSU is time to 100ppm stable output frequency after VDD is applied and outputs are enabled.
4. Output Waveform and Test Circuit figures below define the parameters.
5. Period Jitter includes crosstalk from adjacent output.

Nominal Performance Parameters (Unless specified otherwise: T = 25°C, VDD = 3.3V)

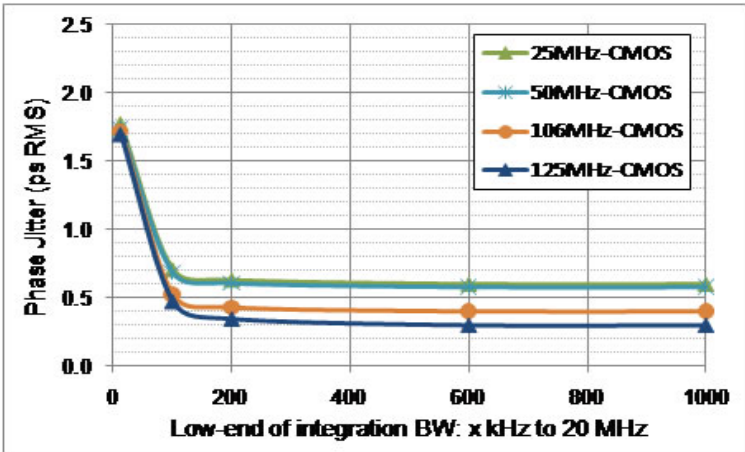


Figure 1. LVC MOS Phase Jitter (integrated phase noise)

LVC MOS Output Waveform

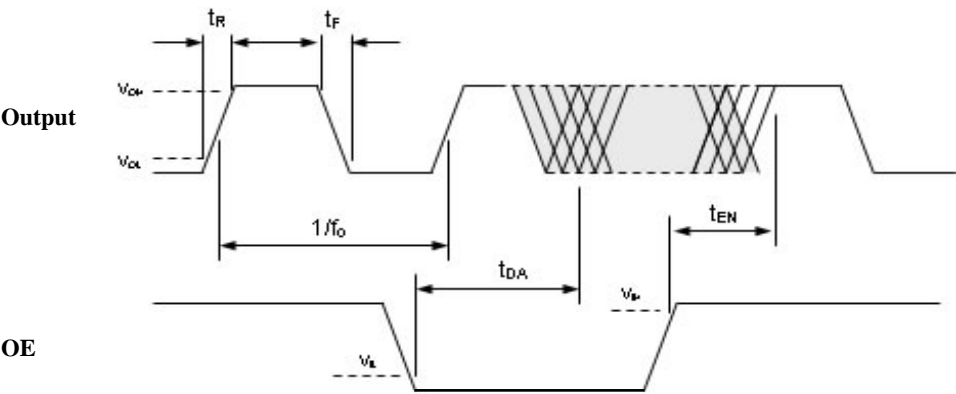


Figure 2. LVC MOS Output Waveform

| MSL 1 @ 260°C refer to JSTD-020C | |
|-----------------------------------|--------------|
| Ramp-Up Rate (200°C to Peak Temp) | 3°C/sec Max. |
| Preheat Time 150°C to 200°C | 60 - 180 sec |
| Time maintained above 217°C | 60 - 150 sec |
| Peak Temperature | 255 - 260°C |
| Time within 5°C of actual Peak | 20 - 40 sec |
| Ramp-Down Rate | 6°C/sec Max. |
| Time 25°C to Peak Temperature | 8 min Max. |

Solder Reflow Profile

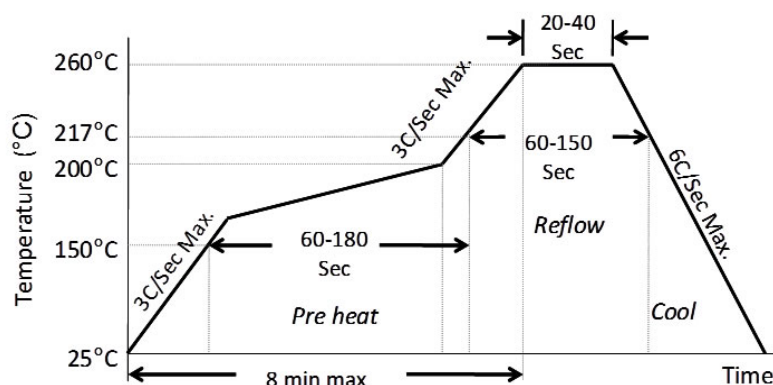
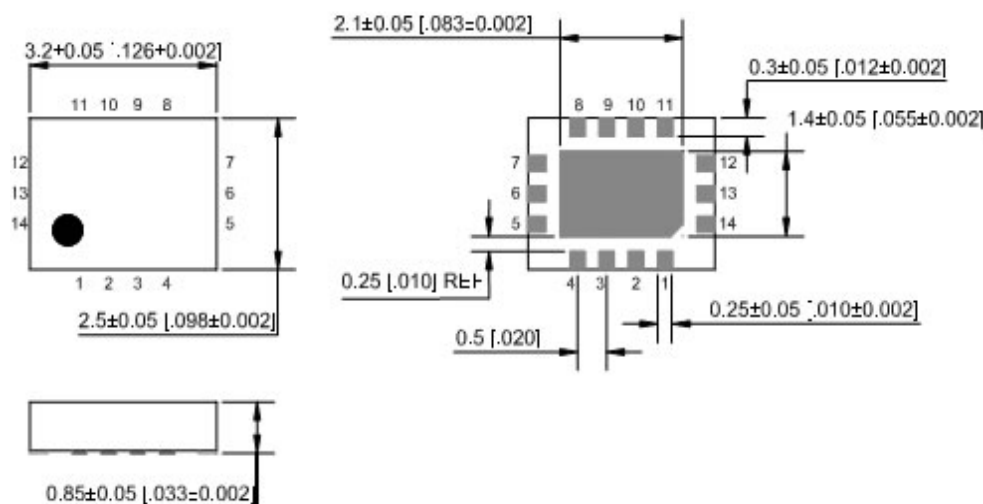


Figure 3. Solder Reflow Profile

Package Information⁷

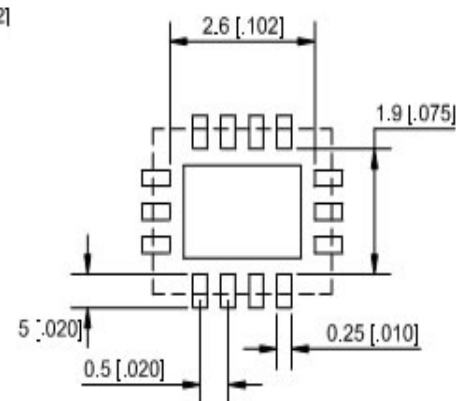
External Dimensions

units: mm[inch]



Recommended Solder Pad Layout

units: mm[inch]



Notes:

3.2mm x 2.5mm 14 Lead Plastic Package

6. Connect the exposed die paddle to ground.

7. Package information is correct as of the publication date. For updates and most current information, go to www.micrel.com.

Micrel makes no representations or warranties with respect to the accuracy or completeness of the information furnished in this data sheet. This information is not intended as a warranty and Micrel does not assume responsibility for its use. Micrel reserves the right to change circuitry, specifications and descriptions at any time without notice. No license, whether express, implied, arising by estoppel or otherwise, to any intellectual property rights is granted by this document. Except as provided in Micrel's terms and conditions of sale for such products, Micrel assumes no liability whatsoever, and Micrel disclaims any express or implied warranty relating to the sale and/or use of Micrel products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright or other intellectual property right.

Micrel products are not designed or authorized for use as components in life support appliances, devices or systems where malfunction of a product can reasonably be expected to result in personal injury. Life support devices or systems are devices or systems that (a) are intended for surgical implant into the body or (b) support or sustain life, and whose failure to perform can be reasonably expected to result in a significant injury to the user. A Purchaser's use or sale of Micrel Products for use in life support appliances, devices or systems is a Purchaser's own risk and Purchaser agrees to fully indemnify Micrel for any damages resulting from such use or sale.

© 2015 Micrel, Incorporated.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Microchip:](#)

[DSC2211FL2-E0018T](#) [DSC2211FL2-E0018](#)